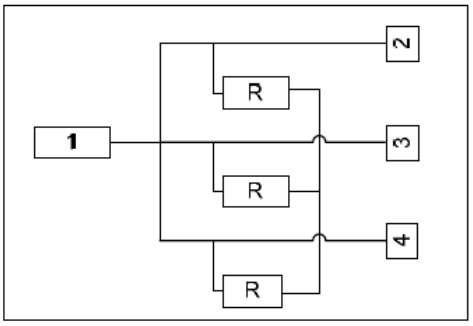
Features

- Frequency: 18-40GHz
- Insertion Loss: 0.7dB Typical
- Isolation: 20dB Typical
- Input/Output: 50Ω
- Chip Size: 1.575 x 0.965 x 0.1mm

Functional Block Diagram



Typical Applications

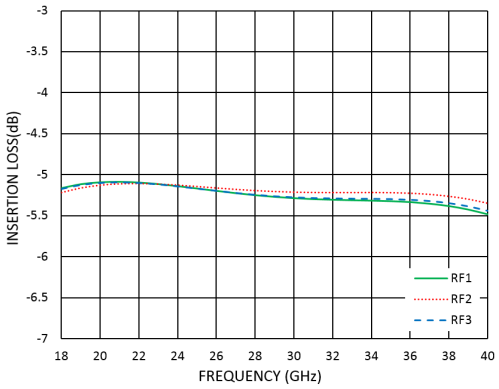
- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- Fiber Optics

Electrical Specifications

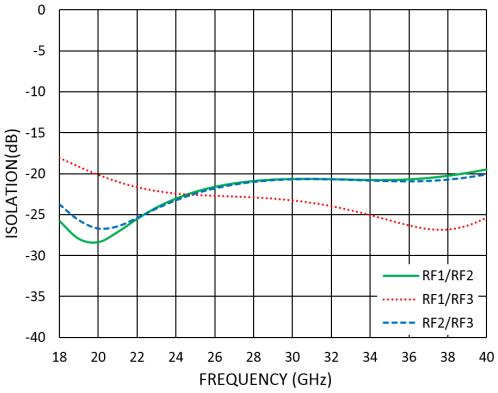
TA = +25°C ,Pin=0dBm

Parameters	Min.	Typ.	Max.	Units
Frequency	18		40	GHz
Nominal Splitter Loss		4.8		dB
Insertion Loss		0.7	1.4	dB
Insertion Loss Flatness		±0.4		dB
Isolation	17	20		dB
Input Return Loss	14	15		dB
Output Return Loss	16	22		dB

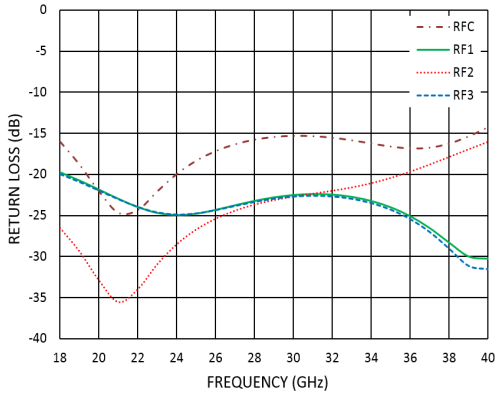
Insertion Loss vs. Frequency



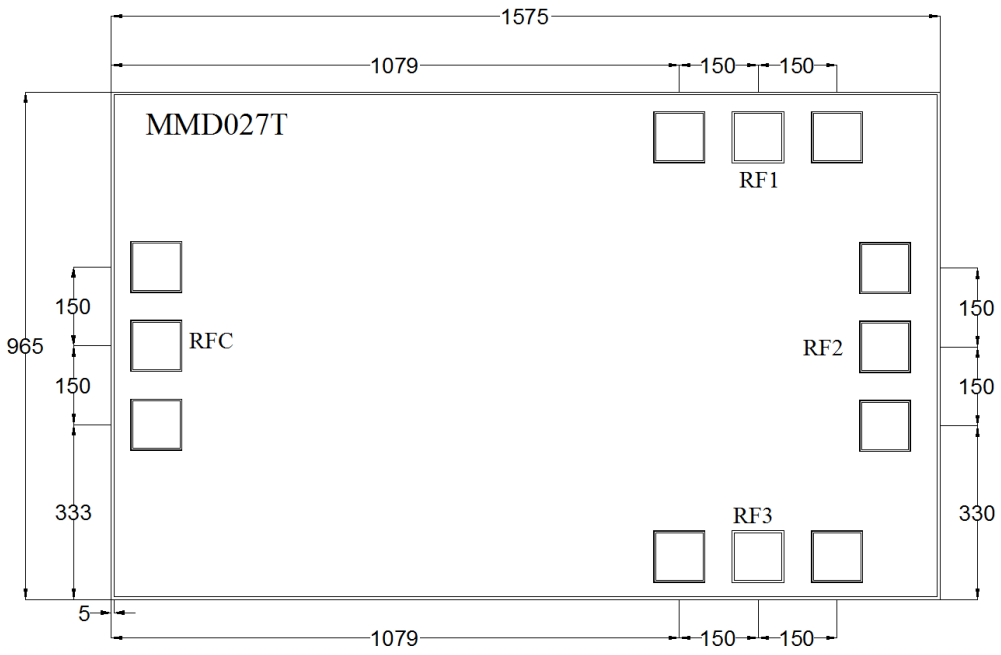
Isolation vs. Frequency



Return Loss vs. Frequency



Outline Drawing: All Dimensions in µm



Absolute Maximum Ratings

RF Input Power	+40dBm
Operating Temperature	-55°C to +85 °C
Storage Temperature	-65°C to +150 °C

No	Symbol	Description
1	RFC	RF Common Port
2,3,4	RF1&RF2 &RF3	RF Branch Ports

Notes:

1. Die thickness: 100µm
2. RF IN/OUT bond pad is 100*100µm^2
3. Bond pad metalization: Gold
4. Backside metalization: Gold
5. Backside of the die (GND)